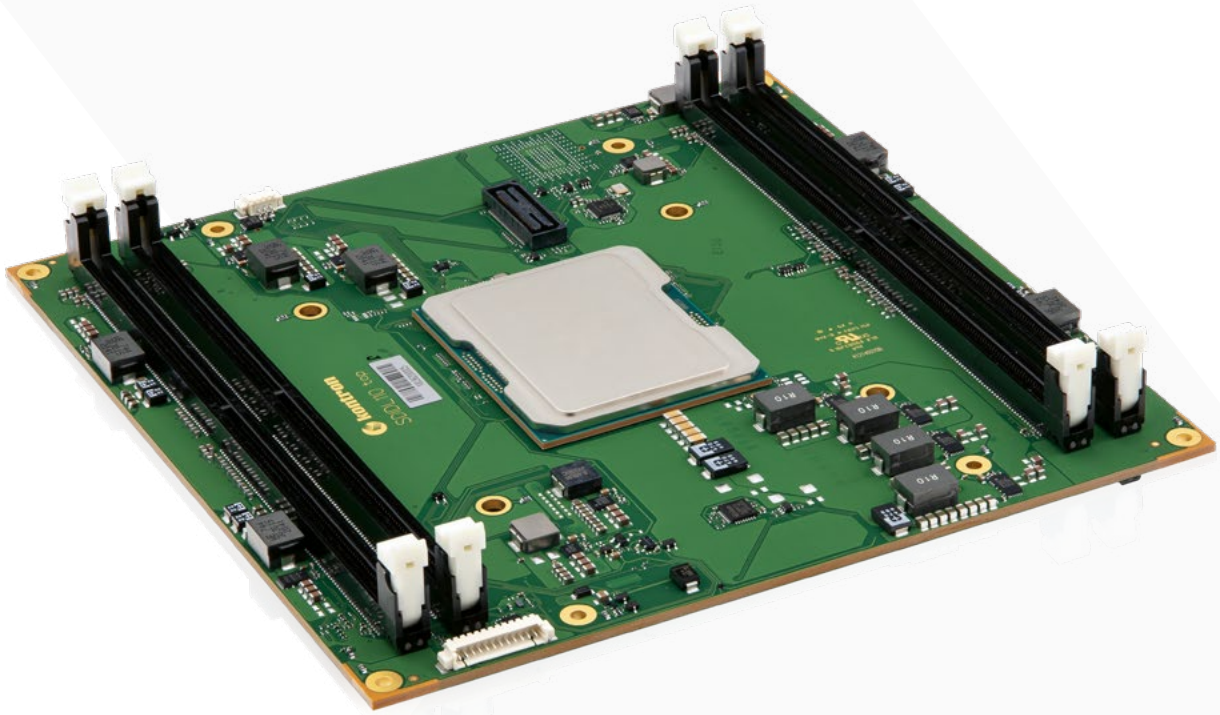


# COMh-sdID (E2)



## COM+HPC®

### COM-HPC®/Server Size D with Intel® XEON® D-2700 / D-2800 SOC processors

- High-end server-grade platform
- 8x LAN Ports: versatile configurations up to 100G
- High-speed connectivity 32x PCIe 4.0 + 16x PCIe 3.0, SATA, USB 3.0
- Up to 1 TByte NVMe SSD onboard
- Industrial grade versions

<b>COMPLIANCE</b>	COM-HPC®/Server, Size D
<b>DIMENSIONS</b>	160 x 160 mm
<b>CPU (SoC)</b>	Intel Xeon® D-2700 / D-2800 Processor Series For details see table "CPU variants" given below
<b>CHIPSET</b>	-
<b>MAIN MEMORY</b>	4x DDR4 DIMM sockets for up to 256 GByte RDIMM (512 GByte planned)
<b>ETHERNET CONTROLLER</b>	Intel® I226-LM/IT Intel® 2x Quad 25GbE LAN integrated in SoC
<b>ETHERNET</b>	1x 1/2.5 Gb Ethernet 8x Ethernet ports supporting versatile configurations: 100GbE/2x 50GbE/4x 25GbE/2x 25GbE + 4x 10GbE/8x 10GbE
<b>STORAGE</b>	2x SATA 6Gb/s
<b>FLASH ONBOARD</b>	Up to 1 TByte NVMe SSD (on request)
<b>PCI EXPRESS®</b>	32x PCIe Gen4 (2 x16, 4 x8, 8 x4) 16x PCIe Gen3 (2 x8, 4 x4, 8 x2)
<b>USB</b>	4x USB 3.0 / USB 2.0
<b>SERIAL</b>	2x serial interface (RX/TX only)
<b>OTHER FEATURES</b>	SPI, eSPI, SMB, Staged Watchdog, RTC
<b>SPECIAL FEATURES</b>	TPM 2.0
<b>FEATURES ON REQUEST</b>	NVMe SSD, 1x PCIe Gen3 for BMC instead of 4th USB3.0
<b>POWER MANAGEMENT</b>	ACPI 6.0
<b>POWER SUPPLY</b>	12V DC
<b>BIOS</b>	AMI UEFI
<b>OPERATING SYSTEM</b>	Linux, Windows 10 IoT Enterprise, Windows Server 2022
<b>TEMPERATURE</b>	Commercial temperature: 0 °C to +60 °C operating, -30 °C to +80 °C non-operating Industrial temperature: -40 °C to +80 °C operating, -40 °C to +80 °C non-operating
<b>HUMIDITY</b>	93 % relative Humidity at 40 °C, non-condensing (according to IEC 60068-2-78)
<b>SUPPORTED MODULES</b>	COMh-sdID xxxxx commercial grade COMh-sdID E2 xxxxx industrial grade

CPU	STD /on request	CORES	TDP, W	IOTG	eTemp	DDR4 1DPC (MT/s)	Ethernet mode	QAT	BASE FREQ (GHZ)	ALL CORE TURBO (GHZ)
D-2796TE	yes	20	118	Yes	Yes	2933	100G	DISABLED	2	2,4
D-2896TER	on request	20	110	Yes	Yes	2933	100G	DISABLED	2	2,5
D-2775TE	yes	16	100	Yes	Yes	2933	100G	DISABLED	2	2,4
D-2752TER	yes	12	77	Yes	Yes	2667	50G	DISABLED	1,8	2,1
D-2733NT	on request	8	80	Yes	No	2667	50G	50G	2,1	2,6
D-2712T	on request	4	65	Yes	No	2667	50G	DISABLED	1,9	2,4
D-2899NT	on request	22	135	No	No	3200	100G	100G	2,2	2,8
D-2798NX	on request	20	126	No	No	2933	100G	100G Inline	2,1	2,6
D-2796NT	yes	20	120	No	No	2933	100G	100G	2	2,5
D-2798NT	on request	20	125	No	No	3200	100G	100G	2,1	2,6
D-2896NT	on request	20	120	No	No	2933	100G	100G	2	2,6
D-2786NTE	on request	18	118	No	Yes	2933	100G	100G	2,1	2,5
D-2777NX	on request	16	116	No	No	2667	100G	100G Inline	2,2	2,7
D-2776NT	on request	16	117	No	No	2933	100G	100G	2,1	2,6
D-2876NT	on request	16	100	No	No	2933	100G	50G	2	2,5
D-2766NT	on request	14	97	No	No	2667	100G	50G	2	2,5
D-2753NT	on request	12	87	No	No	2667	100G	50G	2	2,5
D-2752NTE	on request	12	84	No	Yes	2667	50G	50G	1,9	2,3
D-2757NX	on request	12	107	No	No	2667	50G	50G Inline	2,5	3
D-2745NX	on request	10	96	No	No	2667	50G	50G Inline	2,4	2,9
D-2843NT	on request	10	80	No	No	2667	50G	50G	2	2,6
D-2832NT	on request	8	70	No	No	2667	50G	50G	2,1	2,6
D-2799	on request	20	129	No	No	3200	DISABLED	DISABLED	2,4	2,6
D-2779	on request	16	126	No	No	3200	DISABLED	DISABLED	2,5	2,8
D-2738	on request	8	88	No	No	2933	DISABLED	DISABLED	2,5	3



ARTICLE	PART NO.	DESCRIPTION
COM-HPC/SERVER EVAL-CARRIER	HST01-0000-10-0	Eval-Carrier with 10-mm stack-up connector

## Cooling

ARTICLE	PART NO.	DESCRIPTION
COMh-sdID (E2) HSP THREADED	HSD01-0000-99-0	COMh-sdID (E2) heatspreader threaded
COMh-sdID (E2) HSP THROUGH HOLE	HSD01-0000-99-1	COMh-sdID (E2) heatspreader through hole
COMh SIZE D ACTIVE UNI COOLER (W/O HSP)	HSD99-0000-99-0	COM-HPC Size D Universal Active Cooler for Heatspreader Mounting (160 x 100 x 46 mm)
COMh SIZE D PASSIVE UNI COOLER (W/O HSP)	HSD99-0000-99-1	COM-HPC Size D Universal Passive Cooler for Heatspreader Mounting (160 x 100 x 46 mm)
COOLING COMh-sdID (E2): ADAPTER	HSD01-0000-99-A	Cooling Solution for COMh-sdID (E2), adapter for a standard LGA115x cooling solution. To be used with HSD01-0000-99-B & HSD01-0000-99-C
COOLING COMh-sdID (E2): BACKPLATE	HSD01-0000-99-B	Cooling Solution for COMh-sdID (E2), backplate To be used with HSD01-0000-99-A & HSD01-0000-99-C
COOLING COMh-sdID (E2): COOLER	HSD01-0000-99-C	Cooling Solution for COMh-sdID (E2), LGA115x cooler To be used with HSD01-0000-99-A & HSD01-0000-99-B

## Memory

PART NO.	DESCRIPTION	SIZE	ECC/NON-ECC	OP. TEMPERATURE
97100-0832-SDID	DDR4-3200 RDIMM	8 GByte	ECC	0 °C to +60 °C
97100-1632-SDID	DDR4-3200 RDIMM	16 GByte	ECC	0 °C to +60 °C
97100-3232-SDID	DDR4-3200 RDIMM	32 GByte	ECC	0 °C to +60 °C
97100-6432-SDID	DDR4-3200 RDIMM	64 GByte	ECC	0 °C to +60 °C
97101-0832-SDID	DDR4-3200 RDIMM	8 GByte	ECC	-40 °C to +85 °C
97101-1632-SDID	DDR4-3200 RDIMM	16 GByte	ECC	-40 °C to +85 °C
97101-3232-SDID	DDR4-3200 RDIMM	32 GByte	ECC	-40 °C to +85 °C
97101-6432-SDID	DDR4-3200 RDIMM	64 GByte	ECC	-40 °C to +85 °C

## Global Headquarters

Kontron Europe GmbH

Gutenbergstraße 2  
85737 Ismaning, Germany  
Tel.: + 49 821 4086-0  
info@kontron.com

www.kontron.com

